# MA6Z718 (MA6S718)

### Silicon epitaxial planar type

#### For switching

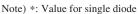
#### Features

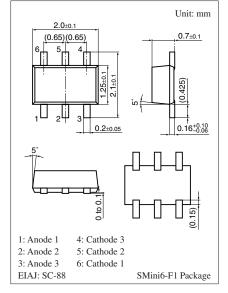
- Three isolated elements are contained in one package, allowing high-density mounting
- $\bullet$  Forward voltage  $V_{\rm F}$  , optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	30	V
Maximum peak reverse voltage	V <sub>RM</sub>	30	V
Peak forward current *	I <sub>FM</sub>	150	mA
Forward current *	$I_F$	30	mA
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

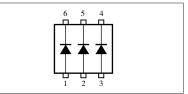
Electrical Characteristics  $T_a = 25^{\circ}C \pm 3^{\circ}C$ 





#### Marking Symbol: M2N

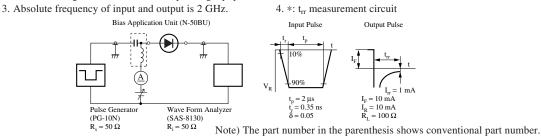
#### Internal Connection

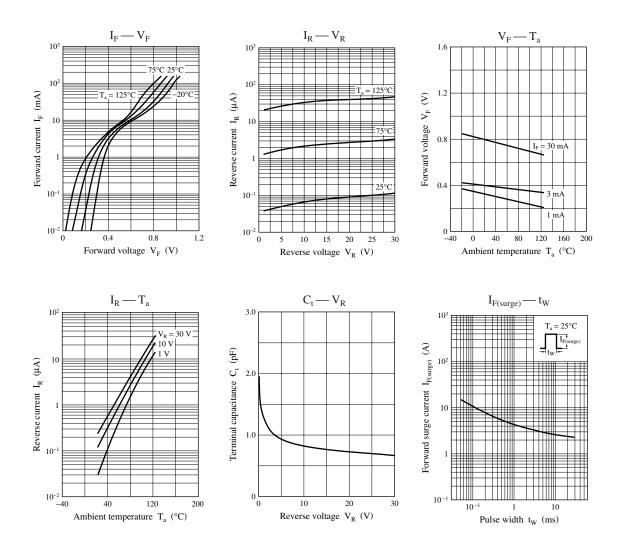


#### Parameter Symbol Conditions Min Unit Typ Max Forward voltage $V_{F1}$ $I_F = 1 \text{ mA}$ 0.4 V V<sub>F2</sub> $I_F = 30 \text{ mA}$ 1.0 Reverse current $I_R$ $V_R = 30 V$ 1 μΑ $V_R = 1 V, f = 1 MHz$ Terminal capacitance 1.5 pF $C_t$ $I_{F} = I_{R} = 10 \text{ mA}$ Reverse recovery time 3 1.0 ns t<sub>rr</sub> $I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$ Detection efficiency $V_{IN} = 3 V_{(peak)}$ , f = 30 MHz 65 % η $R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.





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